



FLIP CHIP MODULES TEST DATA

TYPE: R 131
EXCLUSIVE OR

TEST	CONDITIONS	MAXIMUM	MINIMUM
LOWER LEVEL	/	-3.9 V	-3.2 V
LOAD CURRENT	/	2.2 MA	1.8 MA
LEAKAGE	-0.5, -2.5V IN, 15 MA (8 TESTS)	1.0 μ A	/
V _{CE} SAT.	-0.5, -2.5V IN, 20 MA LOAD (8 TESTS)	230 MV	/
RISE TTT	7.5K LOAD (8 TESTS)	60 NS	/
FALL TTT	7.5K LOAD (8 TESTS)	440 NS	/
SETTLING TIME	7.5K LOAD TIE INPUTS TOGETHER APPLY FF TO INPUT.	260 NS	/

TECHNICAL INFORMATION

Instruction literature and technical bulletins are available on all digital products, if you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

MAINTENANCE INFORMATION

Repair of printed circuitry should be done with a low voltage, fairly cool soldering iron to prevent damage to the transistors and keep the copper from lifting. Oscilloscopes used to troubleshoot a module or system should be grounded to prevent damaging transients.

12/8/66

ELEC. TESTER:	DATE:
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